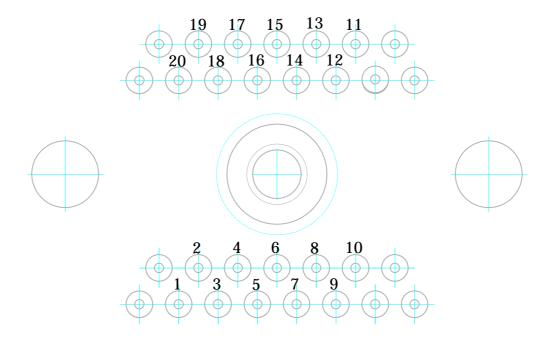
For NSPACK20BK user, Recommended a Footpatern of YSSOCKET30BK Series



* Recommended foot pattern shown on left is for NSPACK soldering. But please refer to IC package foot pattern recommended by IC manufacturer also, when the package is soldered on the same foot pattern.

| Part No. | YSSOCKET30BK | |
|--------------------------------|--------------|--------------|
| IC package | Rectangle | |
| Pin count | 20Pin | |
| Lead pitch | 0.65mm | |
| Unit : mm | | Design : M.H |
| TET TOKYO ELETECH CORP. | | |